

IN THE CLAIMS

1. (Original) A method of forming a device including emitters comprising:  
exposing a first face of a sheet of bundled fiber segments to a reactive liquid to allow first ends of said fiber segments to react with said reactive liquid to remove material therefrom;  
depositing a coating material on said first face with said material removed; and  
exposing a second face of said sheet of bundled fiber segments to a reactive liquid to allow second ends of said fiber segments to react with said reactive liquid to remove material therefrom to expose said coating material.
2. (Original) The method of Claim 1, wherein said reactive liquid comprises a bath of HF acid.
3. (Previously presented) The method of Claim 1, wherein said reactive liquid comprises a spray of HF acid.
4. (Currently amended) The method of Claim 1, wherein said coating material comprises a low electron affinity material taken from the group consisting of  $\alpha$ -C, PdO<sub>x</sub>, Pd, Mo, Ni, Cr, Cu, Au, Pt, Ir, and diamond and the like.
5. (Original) The method of Claim 1, wherein said exposing said first face of said sheet of bundled fiber segments to a reactive liquid comprises removing material from said first ends to form modified ends and cells, wherein depositing said coating material on said

LAW OFFICES OF  
MACPHERSON KIVOK  
CHEN & HEND LLP  
1762 Technology Drive  
Suite 226  
San Jose, CA 95110  
(949) 752-7040  
FAX (949) 752-7040

first face with said material removed comprises depositing said coating material on said modified ends and in said cells.

6. (Original) The method of Claim 1, further comprising forming a dielectric layer on said coating material.

7. (Original) The method of Claim 6, further comprising mounting a substrate on said dielectric layer.

8. (Original) The method of Claim 1, wherein said exposed coating material forms an electron emitter.

9. (Original) The method of Claim 1, further comprising:

providing a transparent substrate having a transparent conductive material deposited thereon;

forming a dielectric spacer on said transparent substrate;

patterning and etching selective areas of said dielectric spacer to form chambers for containing color phosphors; and

aligning said etched selective areas with said exposed coating material to form a field emitter device.

10. (Original) The method of Claim 9, wherein a gate electrode is formed on said dielectric spacer.

11. (Original) The method of Claim 9, further comprising:

LAW OFFICES OF  
MACPHERSON KWOK  
CHEN & HUI LLP  
1762 Technology Drive  
Suite 220  
San Jose, CA 95110  
(949) 752-7040  
FAX (949) 752-7049

depositing a transparent conductive material on said transparent substrate, and patterning said transparent conductive material.

12. (Original) The method of Claim 9, further comprising:

sealing said field emitter device after pumping said field emitter device into vacuum.

13. (Original) The method of Claim 1, wherein a gate electrode layer is deposited and patterned on the second face of said sheet of bundled fiber segments.

LAW OFFICES OF  
MACPHERSON KWOK  
CHEN & HSIAO LLP

1763 Technology Drive  
Suite 226  
San Jose, CA 95110  
(408) 253-2040  
FAX (408) 752-7049